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(54) **Chemical mechanical polishing pad**

(57) The polishing pad is for polishing patterned semiconductor substrates. The pad includes a polymeric matrix and hollow polymeric particles within the polymeric matrix. The polymeric matrix is a polyurethane reaction product of a curative agent and an isocyanate-terminated polytetramethylene ether glycol at an NH₂ to NCO stoichiometric ratio of 80 to 97 percent. The isocyanate-terminated polytetramethylene ether glycol has an unreacted NCO range of 8.75 to 9.05 weight percent. The hollow polymeric particles having an average diameter of 2 to 50 μm and a wt%_b and density_b of constituents forming the polishing pad as follows:

$$\frac{wt\%_a * density_b}{density_a} = wt\%_b$$

where density_a equals an average density of 60 g/l, where density_b is an average density of 5 g/l to 500g/l, where wt%_a is 3.25 to 4.25 wt%. The polishing pad has a porosity of 30 to 60 percent by volume; and a closed cell structure within the polymeric matrix forms a continuous network surrounding the closed cell structure.



EUROPEAN SEARCH REPORT

Application Number
EP 09 15 4680

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
A,D	US 7 169 030 B1 (KULP MARY JO [US]) 30 January 2007 (2007-01-30) * paragraphs [0016], [0018], [0020], [0024], [0025]; example 1 * -----	1-10	INV. B24B37/04 B24D3/32
A	US 2007/275226 A1 (KULP MARY JO [US]) 29 November 2007 (2007-11-29) * paragraphs [0023] - [0033]; example 1 * -----	1-10	
A	US 2008/182492 A1 (CRKVENAC T TODD [US] ET AL) 31 July 2008 (2008-07-31) * paragraphs [0035] - [0044]; example 1 * -----	1-10	
The present search report has been drawn up for all claims			TECHNICAL FIELDS SEARCHED (IPC)
			B24B
Place of search		Date of completion of the search	Examiner
Munich		6 May 2013	Gelder, Klaus
<p>CATEGORY OF CITED DOCUMENTS</p> <p>X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document</p> <p>T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons</p> <p>& : member of the same patent family, corresponding document</p>			

1
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**ANNEX TO THE EUROPEAN SEARCH REPORT
ON EUROPEAN PATENT APPLICATION NO.**

EP 09 15 4680

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report.
The members are as contained in the European Patent Office EDP file on
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06-05-2013

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
US 7169030	B1	30-01-2007	CN 101077569 A 28-11-2007
		DE 102007024460 A1 29-11-2007	
		FR 2901498 A1 30-11-2007	
		JP 2007313640 A 06-12-2007	
		KR 20070114018 A 29-11-2007	
		TW 200813199 A 16-03-2008	
		US 7169030 B1 30-01-2007	

US 2007275226	A1	29-11-2007	CN 101077570 A 28-11-2007
		DE 102007024459 A1 29-11-2007	
		FR 2901499 A1 30-11-2007	
		JP 2007313641 A 06-12-2007	
		KR 20070114019 A 29-11-2007	
		TW 200806431 A 01-02-2008	
		US 2007275226 A1 29-11-2007	

US 2008182492	A1	31-07-2008	CN 101306517 A 19-11-2008
		JP 2008188757 A 21-08-2008	
		KR 20080071089 A 01-08-2008	
		TW 200914588 A 01-04-2009	
		US 2008182492 A1 31-07-2008	
